

CEL

NEC's 4-PIN SOP
LOW OFF-STATE LEAKAGE CURRENT
1-ch OPTICAL COUPLED MOS FET

PS7200U-1A**FEATURES**

- **LOW OFF-STATE LEAKAGE CURRENT:**
 $I_{\text{off}} = 0.1 \text{ nA TYP.}$
- **BREAK DOWN VOLTAGE:**
 $V_L = 80 \text{ V}$
- **HIGH-SPEED TURN-ON TIME:**
 $t_{\text{on}} = 0.05 \text{ ms TYP}$
- **LOW OUTPUT CAPACITANCE:**
 $C_{\text{out}} = 2.3 \text{ pF TYP.}$
- **C × R:**
 $C \times R = 40 \text{ pF} \cdot \Omega$
- **1 CHANNEL TYPE:**
 1a Output
- **DESIGNED FOR AC/DC SWITCHING LINE CHANGER**
- **SMALL AND THIN PACKAGE:**
 4-pin SOP, Height = 2.1 mm
- **LOW OFFSET VOLTAGE**
- **ORDERING NUMBER OF TAPING PRODUCT:**
 PS7200U-1A-E3, E4, F3, F4

DESCRIPTION

NEC's PS7200U-1A is a low output capacitance solid state relay containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

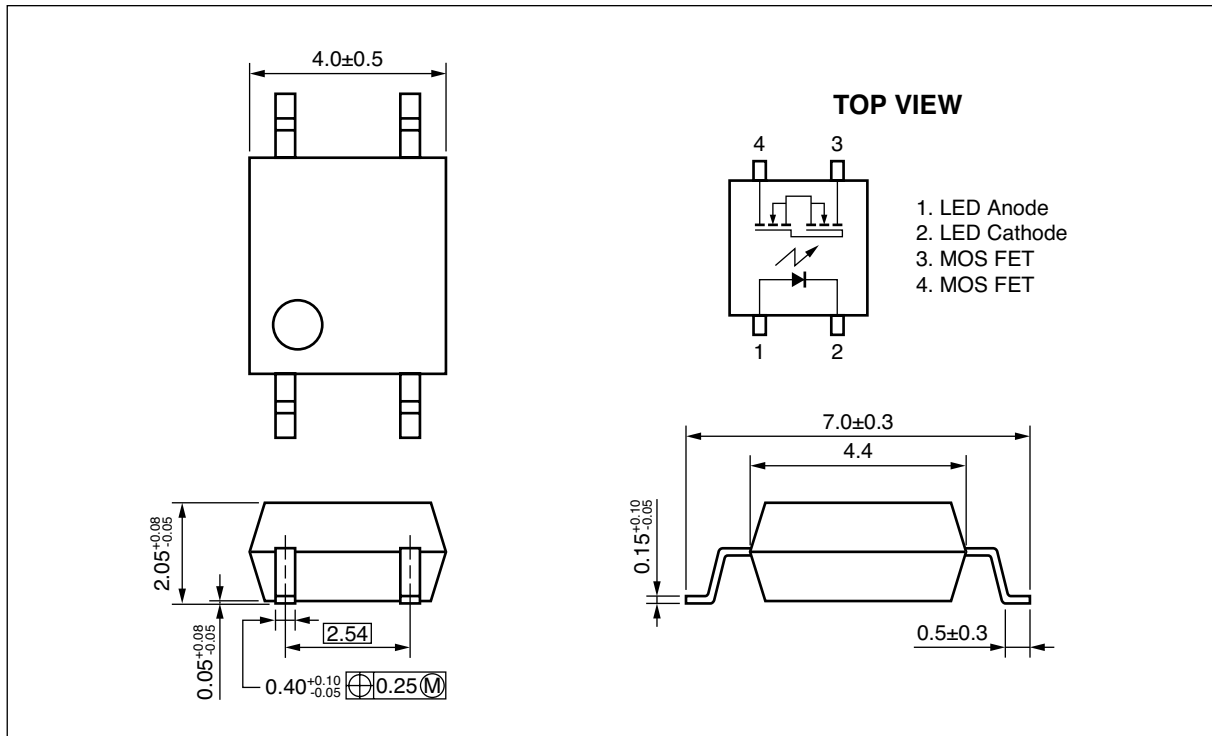
It is suitable for high-frequency signal control, due to its extremely low off-state leakage current, low output capacitance, and high-speed turn-on time.

APPLICATIONS

- **Measurement Equipment**

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PACKAGE DIMENSIONS (UNIT: mm)



ORDERING INFORMATION

PART NUMBER	ORDER NUMBER	SOLDER PLATING SPECIFICATION	PACKING STYLE
PS7200U-1A	PS7200U-1A	Solder contains lead	Magazine case 100 pcs
PS7200U-1A-E3	PS7200U-1A-E3		Embossed Tape 900 pcs/reel
PS7200U-1A-E4	PS7200U-1A-E4		
PS7200U-1A-F3	PS7200U-1A-F3		Embossed Tape 3 500 pcs/reel
PS7200U-1A-F4	PS7200U-1A-F4		
PS7200U-1A	PS7200U-1A-A	Pb-Free	Magazine case 100 pcs
PS7200U-1A-E3	PS7200U-1A-E3-A		Embossed Tape 900 pcs/reel
PS7200U-1A-E4	PS7200U-1A-E4-A		
PS7200U-1A-F3	PS7200U-1A-F3-A		Embossed Tape 3 500 pcs/reel
PS7200U-1A-F4	PS7200U-1A-F4-A		

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Diode	Forward Current (DC)	I _F	50	mA
	Reverse Voltage	V _R	5.0	V
	Power Dissipation	P _D	50	mW
	Peak Forward Current *1	I _{FP}	1	A
MOS FET	Break Down Voltage	V _L	80	V
	Continuous Load Current	I _L	40	mA
	Pulse Load Current*2 (AC/DC Connection)	I _{LP}	80	mA
	Power Dissipation	P _D	300	mW
Isolation Voltage *3		BV	1 500	Vr.m.s.
Total Power Dissipation		P _T	350	mW
Operating Ambient Temperature		T _A	-40 to +85	°C
Storage Temperature		T _{stg}	-40 to +100	°C

*1 PW = 100 μs, Duty Cycle = 1%

*2 PW = 100 ms, 1 shot

*3 AC voltage for 1 minute at T_A = 25 °C, RH = 60% between input and output.
Pins 1-2 shorted together, 3-4 shorted together.

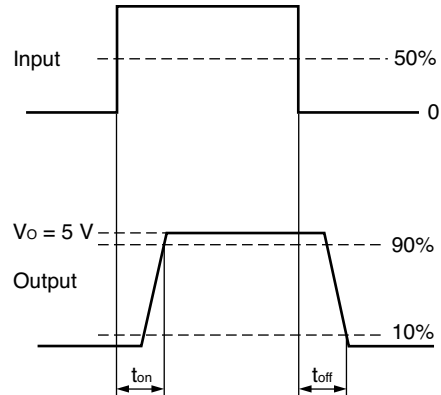
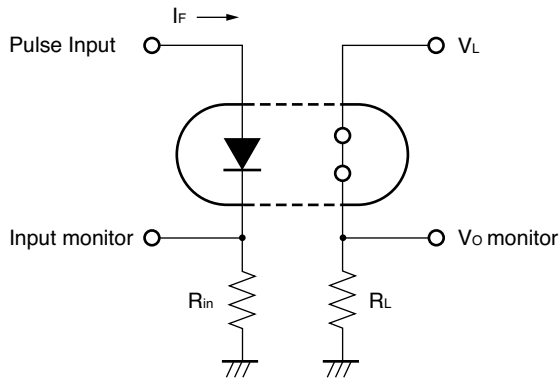
RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
LED Operating Current	IF	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

ELECTRICAL CHARACTERISTICS (TA = 25°C)

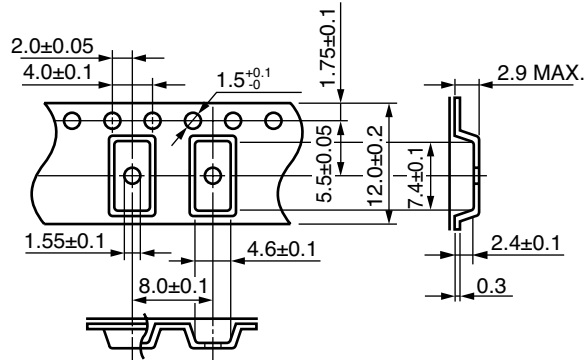
PARAMETER		SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Diode	Forward Voltage	VF	IF = 5 mA		1.1	1.3	V
	Reverse Current	IR	VR = 5 V		0.01	5.0	μA
MOS FET	Off-state Leakage Current	ILoff	Vb = 80 V		0.1	1.0	nA
	Output Capacitance	Cout	Vb = 0 V, f = 1 MHz		2.3	3.5	pF
Coupled	LED On-state Current	IFon	IL = ±40 mA			2.0	mA
	On-state Resistance	Ron	IF = 5 mA, IL = ±40 mA		17	25	Ω
	Turn-on Time*1	ton	IF = 5 mA, VL = 5 V, RL = 500 Ω, PW ≥ 0.5 ms		0.05	0.5	ms
	Turn-off Time*1	toff			0.15	0.5	
	Isolation Resistance	RI-o	VI-o = 1.0 kVDC	10 ⁹			Ω
	Isolation Capacitance	CI-o	V = 0 V, f = 1 MHz		0.3		pF

*1 Test Circuit for Switching Time

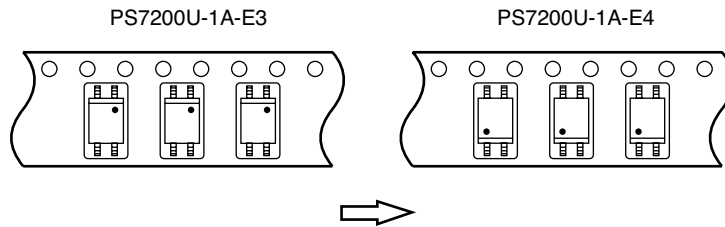


TAPING SPECIFICATIONS (mm)

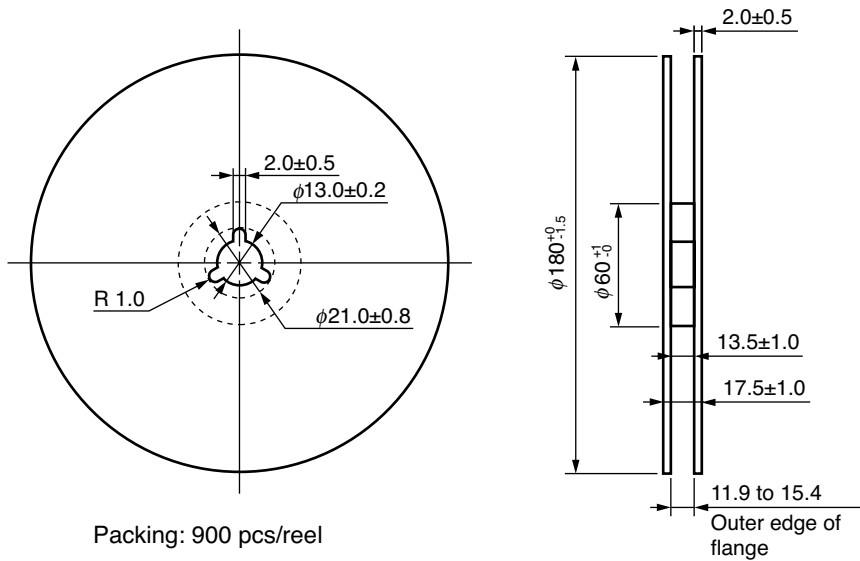
Outline and Dimensions (Tape)



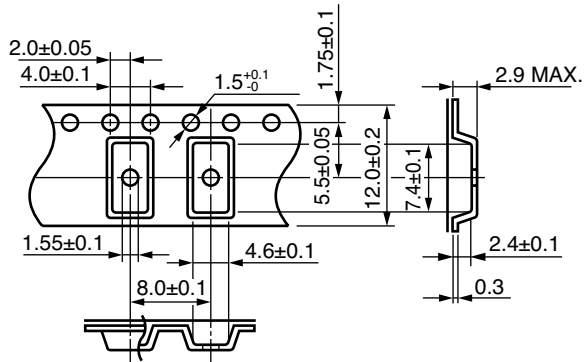
Tape Direction



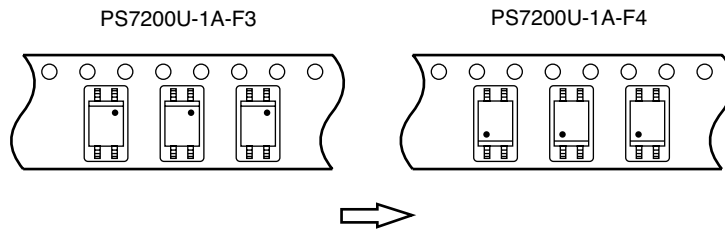
Outline and Dimensions (Reel)



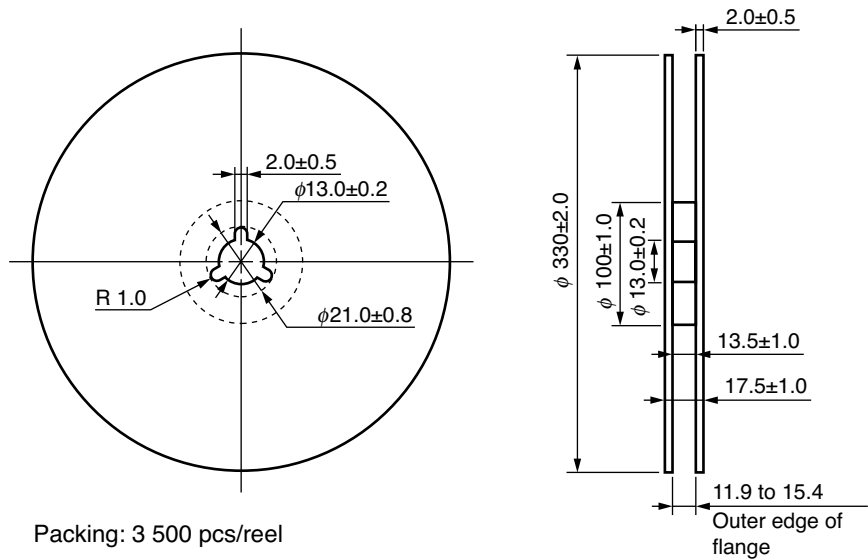
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



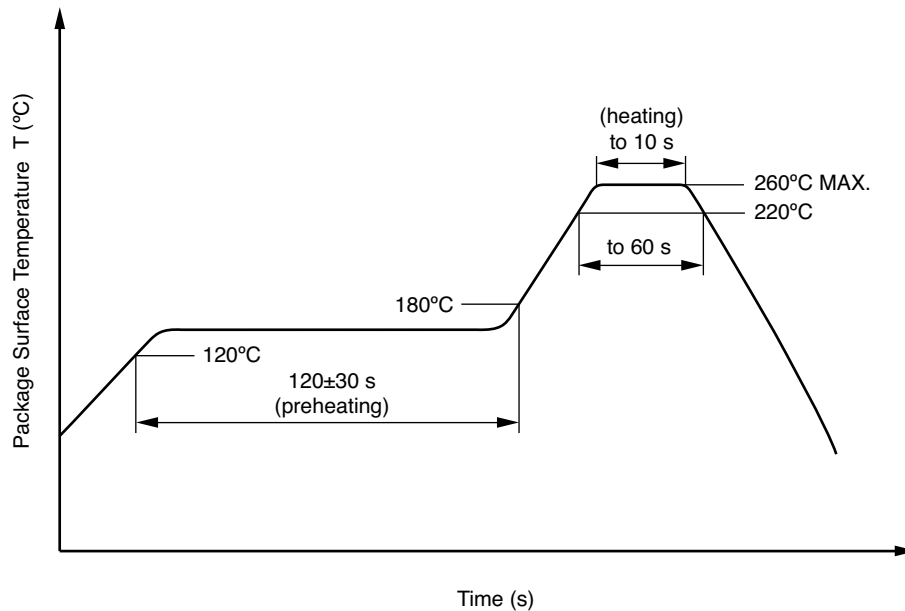
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

- Peak Temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead

(b) Please be sure that the temperature of the package would not be heated over 100°C

(4) Cautions

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

Life Support Applications

These NEC products are not intended for use in life support devices, appliances, or systems where the malfunction of these products can reasonably be expected to result in personal injury. The customers of CEL using or selling these products for use in such applications do so at their own risk and agree to fully indemnify CEL for all damages resulting from such improper use or sale.

CEL California Eastern Laboratories, Your source for NEC RF, Microwave, Optoelectronic, and Fiber Optic Semiconductor Devices.

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